MOLDED PLASTIC PACKAGING OF ELECTRONIC DEVICES

Abstract

Described is a plastic encapsulated electronic device having an integrated circuit unit, a lead frame and a plastic material encapsulating the IC unit and portions of the leads into a sealed package. Each of the leads includes an inner portion adjacent the IC unit, an outer portion laying in a different plane than the inner portion, and a central portion interconnecting the inner and the outer portions. The plastic enclosure is so formed that the outer portion of each lead, except for its lowermost flat surface and a short outermost section, is embedded in the plastic material. The bottom surface of the plastic enclosure is substantially coplanar with the lowermost flat surface of each lead. The short outermost portion of the outer lead portion extends beyond the plastic material for testing purposes. This arrangement provides for a robust encapsulation of the leads avoiding the prior problems of the prior art. Additionally, this device is especially useful for attaching the device to an interconnecting board by means of conductive adhesives.

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